19-5328; Rev 0; 7/10

EVALUATION KIT AVAILABLE



0 to 16V, Hot-Swap Controller with 10-Bit Current, Voltage Monitor, and 4 LED Drivers

General Description

The MAX5978 hot-swap controller provides complete protection for systems with a supply voltage from 0 to 16V. The device includes four programmable LED outputs.

The IC provides two programmable levels of overcurrent circuit-breaker protection: a fast-trip threshold for a fast turn-off, and a lower slow-trip threshold for a delayed turn-off. The maximum overcurrent circuitbreaker threshold range is set with a trilevel logic input (IRNG), or by programming through the I²C interface.

The IC is an advanced hot-swap controller that monitors voltage and current with an internal 10-bit ADC, which is continuously multiplexed to convert the output voltage and current at 10ksps. Each 10-bit sample is stored in an internal circular buffer so that 50 past samples of each signal can be read back through the I²C interface at any time or after a fault condition.

The device includes five user-programmable digital comparators to implement overcurrent warning and two levels of overvoltage/undervoltage detection. When measured values violate the programmable limits, an external ALERT output is asserted. In addition to the ALERT signal, the IC can be programmed to deassert the powergood signal and/or turn off the external MOSFET.

The IC features four I/Os that can be independently configured as general-purpose input/outputs (GPIOs) or as open-drain LED drivers with programmable blinking. These four I/Os can be configured for any mix of LED driver or GPIO function.

The device is available in a 32-pin thin QFN-EP package and operates over the -40°C to +85°C extended temperature range.

Ordering Information

PART	TEMP RANGE	PIN-PACKAGE
MAX5978ETJ+	-40°C to +85°C	32 TQFN-EP*

+Denotes a lead(Pb)-free/RoHS-compliant package. *EP = Exposed pad.

_Features

- Hot-Swap Controller Operates from 0 to 16V
- 10-Bit ADC Monitors Load Voltage and Current
- Circular Buffers Store 5ms of Current and Voltage Measurements
- Internal Charge Pump Generates n-Channel MOSFET Gate Drive
- Internal 500mA Gate Pulldown Current for Fast Shutdown
- ◆ VariableSpeed/Bilevel[™] Circuit-Breaker Protection
- Precision-Voltage Enable Input
- Alert Output Indicates Fault and Warning Conditions
- Open-Drain Power-Good Output with Programmable Polarity
- Open-Drain Fault Output
- Four Open-Drain General-Purpose Outputs Sink 25mA to Directly Drive LEDs
- Programmable LED Flashing Function
- Latched-Off Fault Management
- 400kHz I²C Interface
- Small, 5mm x 5mm, 32-Pin TQFN-EP Package

Applications

Blade Servers DC Power Metering Disk Drives/DASD/Storage Systems Soft-Switch for ASICs, FPGAs, and Microcontrollers Network Switches/Routers

VariableSpeed/Bilevel is a trademark of Maxim Integrated Products, Inc.

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For pricing, delivery, and ordering information, please contact Maxim Direct at 1-888-629-4642, or visit Maxim's website at www.maxim-ic.com.

ABSOLUTE MAXIMUM RATINGS

IN, SENSE, MON, GATE to AGND0.3V to +30V LED_ to AGND0.3V to +16V
PG, ON, ALERT, FAULT, SDA, SCL to AGND0.3V to +6V
REG, DREG, IRNG, MODE, PROT, A_ to AGND0.3V to +4V
REG to DREG0.3V to +0.3V
HWEN, POL to AGND0.3V to (V _{REG} + 0.3V)
GATE to MON0.3V to +6V
GND, DGND to AGND0.3V to +0.3V
SDA, ALERT Current
LED_ Current20mA to +100mA
GATE, MON, GND Current750mA

*As per JEDEC51 Standard (Multilayer Board).

Note 1: Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a fourlayer board. For detailed information on package thermal considerations, refer to <u>www.maxim-ic.com/thermal-tutorial</u>.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

 $(V_{IN} = 2.7V \text{ to } 16V, T_A = -40^{\circ}C \text{ to } +85^{\circ}C, \text{ unless otherwise noted. Typical values are at } V_{IN} = 3.3V \text{ and } T_A = +25^{\circ}C.)$ (Note 2)

PARAMETER	SYMBOL		CONDITIONS	MIN	ТҮР	MAX	UNITS	
Supply Input Voltage Range	VIN			2.7		16	V	
Hot-Swap Voltage Range				0		16	V	
Supply Current	lin				2.5	4	mA	
Internal LDO Output Voltage	REG	I _{REG} = 0 to	5mA, $V_{IN} = 2.7V$ to 16V	2.49	2.53	2.6	V	
Undervoltage Lockout	UVLO	VIN rising				2.6	V	
Undervoltage-Lockout Hysteresis	UVLOHYS				100		mV	
CURRENT-MONITORING FUI	NCTION							
MON, SENSE Input Voltage Range				0		16	V	
SENSE Input Current		VSENSE, VM	ON = 16V		32	75	μA	
MON Input Current		VSENSE, VM	ON = 16V		180	280	μA	
		25mV range		24.34		μV		
Current Measurement LSB Voltage		50mV range		48.39				
vollage		100mV rang		96.77				
			VSENSE - VMON = 5mV	-6.57		+6.22	-	
Current Measurement Error		VMON = 0V	VSENSE - VMON = 20mV	-6.71		+6.82		
(25mV Range)		VMON =	VSENSE - VMON = 5mV	-9.71		+8.92	%FS	
		2.5V to 16V	VSENSE - VMON = 20mV	-10.24		+9.36		
		VMON = 0V	VSENSE - VMON = 10mV	-4.24		+3.78		
Current Measurement Error	t Measurement Error		VSENSE - VMON = 40mV	-4.53		+5.36	- %FS	
(50mV Range)		VMON =	VSENSE - VMON = 10mV	-4.50		+4.00] /ofð	
		2.5V to 16V	VSENSE - VMON = 40mV	-4.20		+4.50		

M/X/M

ELECTRICAL CHARACTERISTICS (continued)

 $(V_{IN} = 2.7V \text{ to } 16V, T_A = -40^{\circ}C \text{ to } +85^{\circ}C, \text{ unless otherwise noted. Typical values are at } V_{IN} = 3.3V \text{ and } T_A = +25^{\circ}C.)$ (Note 2)

PARAMETER	SYMBOL		CONDITIONS	MIN	TYP	MAX	UNITS
			VSENSE - VMON = 20mV	-2.70		+2.43	
Current Measurement Error		VMON = 0V	VSENSE - VMON = 80mV	-3.63		+4.56	
(100mV Range)		V _{MON} =	VSENSE - VMON = 20mV	-3.14		+3.19	%FS
		2.5V to 16V		-3.80		+3.93	
			Circuit breaker, DAC = 102	-2.106		+0.888	
Fast Current-Limit Threshold		VMON = 0V	Circuit breaker, DAC = 255	-2.986		+0.641	
Error (25mV Range)		V _{MON} =	Circuit breaker, DAC = 102	-3.000		+1.000	mV
		2.5V to 16V	Circuit breaker, DAC = 255	-3.500		+1.500	
			Circuit breaker, DAC = 102	-3.1188		+0.926	
Fast Current-Limit Threshold Error (50mV Range)		VMON = 0V	Circuit breaker, DAC = 255	-4.873		+0.3421	
		VMON =	Circuit breaker, DAC = 102	-3.2668		+0.9228	mV
		2.5V to 16V	Circuit breaker, DAC = 255	-4.7		+1.0212	
			Circuit breaker, DAC = 102	-4.7987		+1.1812	
Fast Current-Limit Threshold		VMON = 0V	Circuit breaker, DAC = 255	-8.9236		+0.202	
Error (100mV Range)		VMON =	Circuit breaker, DAC = 102	-4.9991		+0.6374	mV
		2.5V to 16V	Circuit breaker, DAC = 255	-8.262		+1	
Slow Current-Limit Threshold Error (25mV Range)			Circuit breaker, DAC = 102	-1.7965		+1.5496	mV
		V _{MON} = 0V V _{MON} = 2.5V to 16V	Circuit breaker, DAC = 255	-1.86		+1.5916	
			Circuit breaker, DAC = 102	-2.149		+1.9868	
			Circuit breaker, DAC = 255	-2.2285		+1.9982	
)/	N/ 01/	Circuit breaker, DAC = 102	-2.3992		+1.8723	· mV
Slow Current-Limit Threshold		V _{MON} = 0V V _{MON} = 2.5V to 16V	Circuit breaker, DAC = 255	-2.5146		+2.1711	
Error (50mV Range)			Circuit breaker, DAC = 102	-2.4716		+2.181	
			Circuit breaker, DAC = 255	-2.7421		+2.1152	
			Circuit breaker, DAC = 102	-3.3412		+2.989	
Slow Current-Limit Threshold		VMON = 0V	Circuit breaker, DAC = 255	-3.8762		+3.6789	· mV
Error (100mV Range)		V _{MON} =	Circuit breaker, DAC = 102	-3.2084		+2.7798	
		2.5V to 16V	Circuit breaker, DAC = 255	-3.8424		+2.6483	
Fast Circuit-Breaker Response Time	tFCB	Overdrive =	10% of current-sense range		2		μs
		Overdrive =	Overdrive = 4% of current-sense range		2.4		
Slow Current-Limit Response	tSCB		8% of current-sense range		1.2		ms
Time	1308		16% of current-sense range	0.8			1110
THREE-STATE INPUTS					0.0		
A1, A0, IRNG, MODE, PROT Low Current	I _{IN_LOW}	Input voltage	e = 0.4V	-40			μA
A1, A0, IRNG, MODE, PROT High Current	I _{IN_} HIGH	Input voltage			40	μΑ	
A1, A0, IRNG, MODE, PROT Open Current	IFLOAT	Maximum so state	-4		+4	μA	
A1, A0, IRNG, MODE, PROT Low Voltage		Relative to A	GND			0.4	V

ELECTRICAL CHARACTERISTICS (continued)

 $(V_{IN} = 2.7V \text{ to } 16V, T_A = -40^{\circ}C \text{ to } +85^{\circ}C, \text{ unless otherwise noted. Typical values are at } V_{IN} = 3.3V \text{ and } T_A = +25^{\circ}C.)$ (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
A1, A0, IRNG, MODE, PROT High Voltage		Relative to V _{REG}	-0.24			V
TWO-STATE INPUTS						
HWEN, POL Input Logic Low Voltage					0.4	V
HWEN, POL Input Logic High Voltage			VREG - 0.4			V
HWEN, POL Input Current			-1		+1	μA
ON Input Voltage	Von		0.582	0.592	0.602	V
ON Input Hysteresis	Vonhys			4		%
ON Input Current			-100		+100	nA
TIMING						
				50		
MON to DO Dolov		Register configurable (see Tables 30a and		100		
MON-to-PG Delay		30b)		200		ms
				400]
CHARGE PUMP (GATE)						
Charge-Pump Output Voltage		Relative to VMON, IGATE = 0V	4.5	5.3	5.5	V
Charge-Pump Output Source Current			4	5	6	μA
GATE Discharge Current		VGATE - VMON = 2V		500		mA
OUTPUT (FAULT, PG, ALERT)	1	1			1
Output-Voltage Low		Isink = 3.2mA			0.2	V
Output Leakage Current					1	μA
LED INPUT/OUTPUT						
LED_ Input Threshold Low Level	VIL				0.4	V
LED_ Input Threshold High Level	ViH		1.4			V
LED_ Output Low	Voh	ILED_ = 25mA			0.7	V
LED_ Input Leakage Current (Open Drain)	IGPIO_IX	V _{LED} = 16V	-1		+1	μΑ
LED_ Weak Pullup Current	IPU_WEAK	VLED_ = VIN - 0.65V	2			μA
ADC PERFORMANCE						
Resolution				10		Bits
Maximum Integral Nonlinearity	INL			1		LSB
ADC Total Monitoring Cycle Time			95	100	110	μs

ELECTRICAL CHARACTERISTICS (continued)

 $(V_{IN} = 2.7V \text{ to } 16V, T_A = -40^{\circ}C \text{ to } +85^{\circ}C, \text{ unless otherwise noted. Typical values are at } V_{IN} = 3.3V \text{ and } T_A = +25^{\circ}C.)$ (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	
		16V range	15.23	15.49	15.69		
		8V range	7.655	7.743	7.811] mV	
MON LSB Voltage		4V range	3.811	3.875	3.933		
		2V range	1.899	1.934	1.966		
		16V range	10	25	41		
MON Code 000H to 001H Transition Voltage		8V range	4.7	12	21		
		4V range	2	6	12	- mV	
		2V range	0.5	3	5.5]	
I ² C INTERFACE	-						
Serial-Clock Frequency	fscl				400	kHz	
Bus Free Time Between STOP and START Conditions	tBUF		1.3			μs	
START Condition Setup Time	tsu:sta		0.6			μs	
START Condition Hold Time	thd:Sta		0.6			μs	
STOP Condition Setup Time	tsu:sto		0.6			μs	
Clock High Period	thigh		0.6			μs	
Clock Low Period	tLOW		1.3			μs	
Data Setup Time	tsu:dat		100			ns	
Data Hold Time		Transmit	100				
	thd:dat	Receive	300		900	- ns	
Output Fall Time	toF	$C_{BUS} = 10 pF$ to $400 pF$			250	ns	
Pulse Width of Spike Suppressed	tSP			50		ns	
SDA, SCL Input High Voltage	Vih		1.8			V	
SDA, SCL Input Low Voltage	VIL				0.8	V	
SDA, SCL Input Hysteresis	VHYST			0.22		V	
SDA, SCL Input Current			-1		+1	μA	
SDA, SCL Input Capacitance				15		pF	
SDA Output Voltage	Vol	ISINK = 4mA			0.4	V	

Note 2: All devices 100% production tested at $T_A = +25^{\circ}C$. Limits over the temperature range are guaranteed by design.

SUPPLY CURRENT SUPPLY CURRENT vs. TEMPERATURE vs. SUPPLY VOLTAGE **GATE-DRIVE VOLTAGE vs. VMON** 2.50 3.0 5.20 VGATE REFERRED TO VMON 2.9 5.15 2.8 2.45 2.40 CURRENT (mA) 2.40 2.35 ≥ 5.10 SUPPLY CURRENT (mA) 2.7 GATE-DRIVE VOLTAGE (5.05 2.6 HOT-SWAP CHANNEL ON 2.5 5.00 2.4 4.95 2.3 2.35 4.90 HOT-SWAP CHANNEL OFF 2.2 4.85 2.1 2.0 2.30 4.80 2 4 12 14 16 0 6 8 10 -40 -15 10 35 60 85 0 2 4 6 8 10 12 14 16 SUPPLY VOLTAGE (V) TEMPERATURE (°C) V_{MON} (V) **GATE-DRIVE CURRENT GATE-DRIVE DISCHARGE CURRENT GATE-DRIVE VOLTAGE vs. VIN** vs. (Vgate - Vmon) vs. (Vgate - Vmon) 10 10 5.10 9 0.9 GATE-DRIVE DISCHARGE CURRENT (A) 8 0.8 5.05 GATE-DRIVE CURRENT (µA) 7 0.7 (VGATE - VMON) (V) $V_{MON} = 3.3V$ 5.00 6 0.6 5 0.5 4 0.4 4.95 3 0.3 $V_{MON} = 12V$ 2 0.2 4.90 0.1 1 0 0 4.85 0.5 1.0 1.5 2.0 2.5 3.0 3.5 4.0 4.5 5.0 0 0.5 1.0 1.5 2.0 2.5 3.0 3.5 4.0 4.5 5.0 2 4 10 12 14 0 0 6 8 16 (VGATE - VMON) (V) (VGATE - VMON) (V) V_{IN} (V) SLOW-COMPARATOR TURN-OFF TIME **SLOW-COMPARATOR THRESHOLD ON THRESHOLD VOLTAGE** vs. VOLTAGE OVERDRIVE **VOLTAGE ERROR vs. TEMPERATURE** vs. TEMPERATURE 3.00 10 0.60 25mV SENSE RANGE. 8 0.59 DAC = 191, V_{TH,ST} = 9.36mV 2.50 (V) 39200 0.57 0.56 0.55 0.55 0.54 0.53 RISING **THRESHOLD VOLTAGE ERROR (%)** 6 (in 2.00 2.00 1.50 1.50 4 FALLING 2 0 50mV SENSE RANGE 100mV SENSE RANGE -2 -4 0.53 N 0.52 -6 0.50 25mV SENSE RANGE -8 0.51 0 -10 0.50 0 2 3 4 5 -40 -15 10 35 85 -40 -15 10 85 60 35 60 (VSENSE - VMON) - VTH,ST (mV) TEMPERATURE (°C) TEMPERATURE (°C)

Typical Operating Characteristics

MAX5978

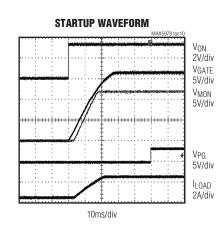
 $(V_{IN} = 3.3V, T_A = +25^{\circ}C, unless otherwise noted.)$

II OAD

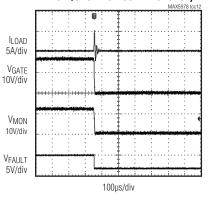
2A/div

Typical Operating Characteristics (continued)

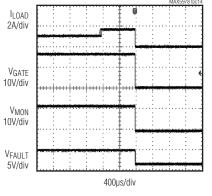
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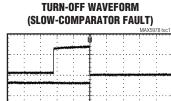


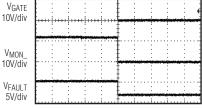




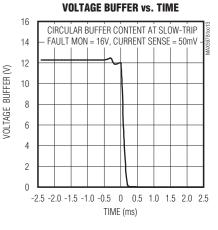
SLOW-COMPARATOR FAULT EVENT



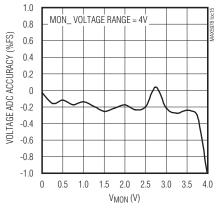




400µs/div



VOLTAGE ADC ACCURACY vs. Mon Voltage

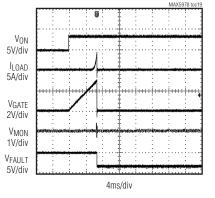


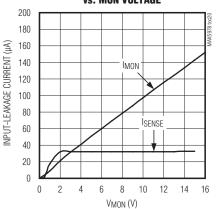
 $(V_{IN} = 3.3V, T_A = +25^{\circ}C, unless otherwise noted.)$ **CURRENT ADC ACCURACY** vs. (Vsense - Vmon) **CURRENT BUFFER vs. TIME VOLTAGE BUFFER vs. TIME** 5 0.5 10 VOLTAGE DATA AT SHORT CIRCUIT ON DEFAULT SETTING 4 9 0.4 POWER-UP DEFAULT SETTING VMON = 16V CURRENT ADC ACCURACY (%FS) 3 8 0.3 2 E 7 0.2 VOLTAGE BUFFER (V) CURRENT BUFFER 1 6 0.1 0 5 0 -1 4 -0.1 3 -2 -0.2 -3 2 -0.3 -4 1 -0.4 -5 0 -0.5 -2.5 -2.0 -1.5 -1.0 -0.5 0 0.5 1.0 1.5 2.0 2.5 2.5 5.0 7.5 10.0 12.5 15.0 17.5 20.0 22.5 25.0 0 -2.5 -2.0 -1.5 -1.0 -0.5 0 0.5 1.0 1.5 2.0 2.5 (VSENSE - VMON) (mV) TIME (ms) TIME (ms) **INPUT LEAKAGE CURRENT**

STARTUP INTO SHORT LOAD

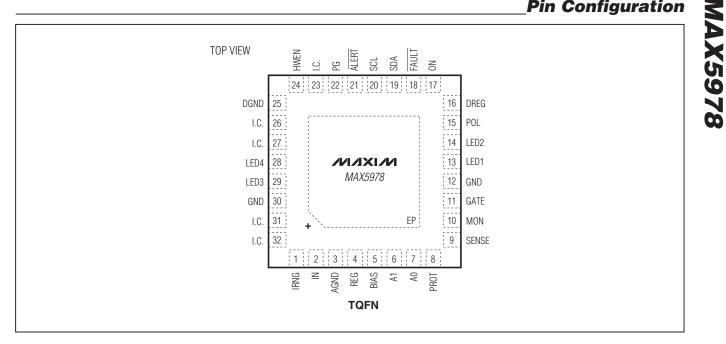


Typical Operating Characteristics (continued)





Pin Configuration

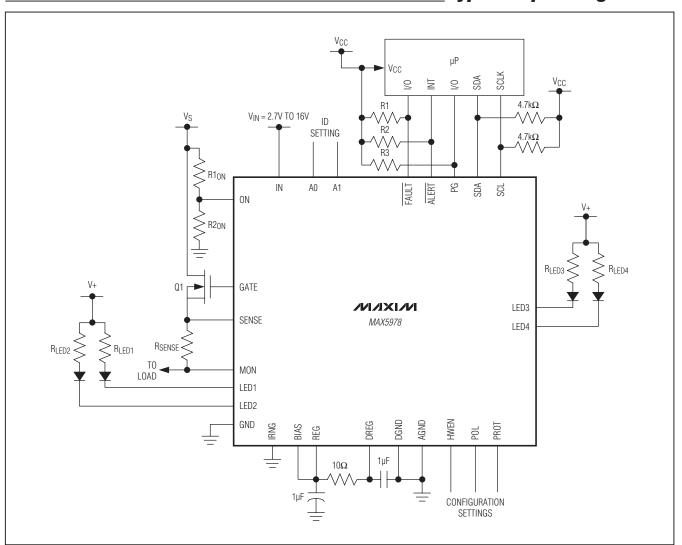


Pin Description

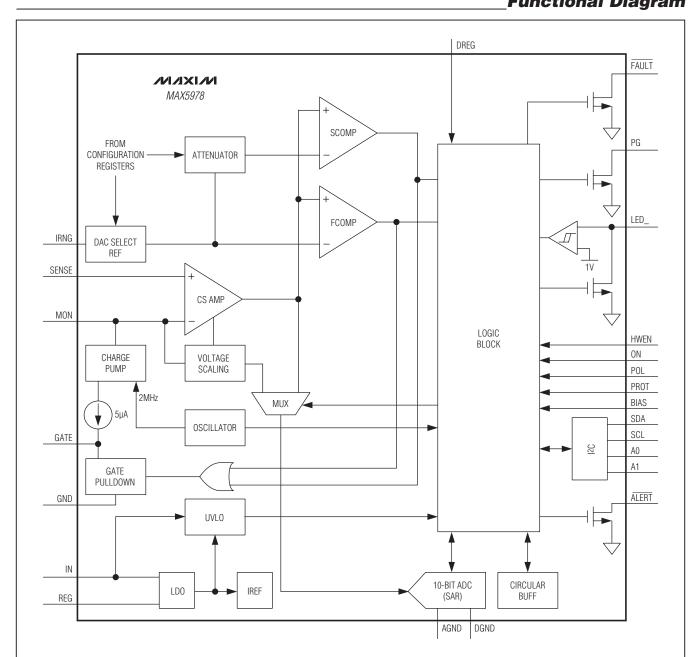
PIN	NAME	FUNCTION
1	IRNG	Three-State Current-Sense Range Selection Input. Set the circuit-breaker threshold range by connecting to DGND, DREG, or leave unconnected.
2	IN	Power-Supply Input. Connect to a voltage from 2.7V to 16V. Bypass IN to AGND with a $1\mu F$ ceramic capacitor.
3	AGND	Analog Ground. Connect all GND and DGND to AGND externally using a star connection.
4	REG	Internal Regulator Output. Bypass REG to ground with a 1µF ceramic capacitor. Connect only to DREG and logic-input pullup resistors. Do not use to power external circuitry.
5	BIAS	BIAS Input. Connect BIAS to REG.
6	A1	Three-State I ² C Address Input 1
7	AO	Three-State I ² C Address Input 0
8	PROT	Protection Behavior Input. Three-state input sets one of three different response options for undervoltage and overvoltage events.
9	SENSE	Current-Sense Input. Connect SENSE to the source of an external MOSFET and to one end of RSENSE.
10	MON	Voltage-Monitoring Input
11	GATE	Gate-Drive Output. Connect to the gate of an external n-channel MOSFET.
12	GND	Gate-Discharge Current Ground Return. Connect all GND and DGND to AGND externally using a star connection.
13	LED1	LED1 Driver
14	LED2	LED2 Driver

PIN	NAME	FUNCTION
15	POL	Polarity Select Input. Connect POL to DREG for an active-high power-good (PG) output, or con- nect POL to GND for active-low PG output.
16	DREG	Logic Power-Supply Input. Connect to REG externally through a 10Ω resistor and bypass to DGND with a 1µF ceramic capacitor.
17	ON	Precision Turn-On Input
18	FAULT	Active-Low Open-Drain Fault Output. FAULT asserts low if an overcurrent event occurs.
19	SDA	I ² C Serial Data Input/Output
20	SCL	I ² C Serial Clock Input
21	ALERT	Open-Drain Alert Output. ALERT goes low during a fault to notify the system of an impending failure.
22	PG	Open-Drain Power-Good Output
23, 26, 27, 31, 32	I.C.	Internally Connected. Connect to ground.
24	HWEN	Hardware Enable Input. Connect to REG or DGND. State is read upon power-up as V_{IN} crosses the UVLO threshold and sets enable register bits with this value. After UVLO, this input becomes inactive until power is cycled.
25	DGND	Digital Ground. Connect all GND and DGND to AGND externally using a star connection.
28	LED4	LED Driver 4
29	LED3	LED Driver 3
30	GND	Ground
	EP	Exposed Pad. EP is internally grounded. Connect EP to the ground plane using a star connection.

Pin Description (continued)



Typical Operating Circuit



Functional Diagram

MAX5978

0 to 16V, Hot-Swap Controller with 10-Bit Current, Voltage Monitor, and 4 LED Drivers

Detailed Description

The MAX5978 includes a set of registers that are accessed through the I^2C interface. Some of the registers are read only and some of the registers are read and write registers that can be updated to configure the device for a specific operation. See Tables 1a and 1b for the register maps.

Hot-Swap Channel On-Off Control

Depending on the configuration of the EN1 and EN2 bits, when V_{IN} is above the V_{UVLO} threshold and the ON input reaches its internal threshold, the device turns on the external n-channel MOSFET for the hot-swap channel, allowing power to flow to the load. The channel is enabled depending on the output of a majority function.

EN1, EN2, and ON are the inputs to the majority function and the channel is enabled when two or more of these inputs are 1:

 $(Channel enabled) = (EN1 \times EN2) + (EN1 \times ON) + (EN2 \times ON)$

Inputs ON and EN2 can be set externally; the initial state of the EN2 bit in register chxen is set by the state of the HWEN input when VIN rises above VUVLO. The ON input connects to an internal precision analog comparators with a 0.6V threshold. Whenever VON is above 0.6V, the ON bit in register status1[0] is set to 1. Inputs EN1 and EN2 can be set using the I²C interface; the EN1 bit has a default value of 0. This makes it possible to enable or disable the hot-swap channel with or without using the I²C interface (see Tables 2, 3a, and 3b).

REGISTER NAME	DESCRIPTION	REGISTER NUMBER	RESET VALUE	READ/ WRITE
adc_cs_msb	High 8 bits ([9:2]) of latest current-signal ADC result	0x00	0x00	R
adc_cs_lsb	Low 2 bits ([1:0]) of latest current-signal ADC result	0x01	0x00	R
adc_mon_msb	High 8 bits ([9:2]) of latest voltage-signal ADC result	0x02	0x00	R
adc_mon_lsb	Low 2 bits ([1:0]) of latest voltage-signal ADC result	0x03	0x00	R
min_cs_msb	High 8 bits ([9:2]) of current-signal minimum value	0x08	0xFF	R
min_cs_lsb	Low 2 bits ([1:0]) of current-signal minimum value	0x09	0x03	R
max_cs_msb	High 8 bits ([9:2]) of current-signal maximum value	0x0A	0x00	R
max_cs_lsb	Low 2 bits ([1:0]) of current-signal maximum value	0x0B	0x00	R
min_mon_msb	High 8 bits ([9:2]) of voltage-signal minimum value	0x0C	0xFF	R
min_mon_lsb	Low 2 bits ([1:0]) of voltage-signal minimum value	0x0D	0x03	R
max_mon_msb	High 8 bits ([9:2]) of voltage-signal maximum value	0x0E	0x00	R
max_mon_lsb	Low 2 bits ([1:0]) of voltage-signal maximum value	0x0F	0x00	R
uv1th_msb	High 8 bits ([9:2]) of undervoltage warning (UV1) threshold	0x1A	0x00	R/W
uv1th_lsb	Low 2 bits ([1:0]) of undervoltage warning (UV1) threshold	0x1B	0x00	R/W
uv2th_msb	High 8 bits ([9:2]) of undervoltage critical (UV2) threshold	0x1C	0x00	R/W
uv2th_lsb	Low 2 bits ([1:0]) of undervoltage critical (UV2) threshold	0x1D	0x00	R/W
ov1thr_msb	High 8 bits ([9:2]) of overvoltage warning (OV1) threshold	0x1E	0xFF	R/W
ov1thr_lsb	Low 2 bits ([1:0]) of overvoltage warning (OV1) threshold	0x1F	0x03	R/W
ov2thr_msb	High 8 bits ([9:2]) of overvoltage critical (OV2) threshold	0x20	0xFF	R/W
ov2thr_lsb	Low 2 bits ([1:0]) of overvoltage critical (OV2) threshold	0x21	0x03	R/W
oithr_msb	High 8 bits ([9:2]) of overcurrent warning threshold	0x22	0xFF	R/W
oithr_lsb	Low 2 bits ([1:0]) of overcurrent warning threshold	0x23	0x03	R/W
dac_fast	Fast-comparator threshold DAC setting	0x2E	0xBF	R/W
cbuf_ba_v	Base address for block read of 50-sample voltage-signal data buffer	0x46		R
cbuf_ba_i	Base address for block read of 50-sample current-signal data buffer	0x47		R

Table 1a. Register Address Map (Channel Specific)

REGISTER NAME	DESCRIPTION	ADDRESS (HEX CODE)	RESET VALUE	READ/ WRITE
mon_range	MON input range setting	0x18	0x00	R/W
cbuf_chx_store	Selective enabling of circular buffer	0x19	0x0F	R/W
ifast2slow	Current threshold fast-to-slow ratio setting	0x30	0x0F	R/W
status0	Slow-trip and fast-trip comparators status register	0x31	0x00	R
status1	PROT, MODE, and ON inputs status register	0x32	_	R
status2	Fast-trip threshold maximum range setting bits, from IRNG three- state input	0x33	_	R/W
status3	LATCH, POL, ALERT, and PG status register	0x34		R
fault0	Status register for undervoltage detection (warning or critical)	0x35	0x00	R/C
fault1	Status register for overvoltage detection (warning or critical)	0x36	0x00	R/C
fault2	Status register for overcurrent detection (warning)	0x37	0x00	R/C
pgdly	Delay setting between MON measurement and PG assertion	0x38	0x00	R/W
fokey	Load register with 0xA5 to enable force-on function	0x39	0x00	R/W
foset	Register that enables force-on function	0x3A	0x00	R/W
chxen	Channel enable bits	0x3B	_	R/W
dgl_i	OC deglitch enable bits	0x3C	0x00	R/W
dgl_uv	UV deglitch enable bits	0x3D	0x00	R/W
dgl_ov	OV deglitch enable bits	0x3E	0x00	R/W
cbufrd_hibyonly	Circular buffers readout mode: 8 bit or 10 bit	0x3F	0x0F	R/W
cbuf_dly_stop	stop Circular buffer stop delay; number of samples recorded to the circu- lar buffer after channel shutdown		0x19	R/W
peak_log_rst	Reset control bits for peak-detection registers	0x41	0x00	R/W
peak_log_hold	Hold control bits for peak-detection registers	0x42	0x00	R/W
LED_flash	LED flash/GPIO enable register	0x43	0x0F	R/W
LED_ph_pu	LED phase/weak pullup enable register	0x44	0x00	R/W
LED_state	LED pins voltage state register (LED pins set open)	0x45		R

Table 1b. Register Address Map (General)

Table 2. chxen Register Format

Description:		Channel enable bits						
Resister Title	:	chxen						
Register Add	ress:	0x3B						
								RESET
R	R	R	R	R/W	R/W	R/W	R/W	VALUE
	—	—	_	Unused	Unused	EN2	EN1	$\neg - $
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	

REGISTER ADDRESS	BIT RANGE	DESCRIPTION					
		ON input state					
		1 = ON above 600mV channel enable threshold					
	[1:0]	0 = ON below 600mV channel enable threshold					
		Bit 0: ON input state					
		Bit 1: unused					
0x32	[4]	Unused					
		Voltage critical behavior (PROT input)					
		00 = Assert ALERT upon UV/OV critical (same as UV/OV warning behavior)					
	[7:6]	01 = Assert ALERT and deassert PG upon UV/OV critical					
		10 = Assert ALERT, deassert PG, and shut down channel upon UV/OV critical					
		11 = (Not possible)					

Table 3a. Register Function

Table 3b. status1 Register Format

Description:		Fault-dete	Fault-detection behavior (three-state PROT input) and ON input status register							
Resister Title:		status1								
Register Addr	ess:	0x32								
								RESET		
R	R	R	R	R	R	R	R	VALUE		
prot[1]	prot[0]	_	Unused	—	—	Unused	ON			
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0			

Figure 1 shows the detailed logic operation of the hotswap enable signals EN1, EN2, and ON, as well as the effect of various fault conditions.

An input undervoltage threshold control for enabling the hot-swap channel can be implemented by placing a resistive divider between the drain of the hot-swap MOSFET and ground, with the midpoint connected to ON. The turn-on threshold voltage for the channel is then:

$V_{EN} = 0.6V \times (R1 + R2)/R2$

The maximum rating for the ON input is 6V; do not exceed this value.

Startup

When all conditions for channel turn-on are met, the external n-channel MOSFET switch is fully enhanced with a typical gate-to-source voltage of 5V to ensure a low drain-to-source resistance. The charge pump at the GATE driver sources 5μ A to control the output voltage turn-on voltage slew rate. An external capacitor can be added from GATE to GND to further reduce the

voltage slew rate. Placing a $1k\Omega$ resistor in series with this capacitance prevents the added capacitance from increasing the gate turn-off time. Total inrush current is the load current summed with the product of the gate-voltage slew rate dV/dt and the load capacitance.

To determine the output dV/dt during startup, divide the GATE pullup current IG(UP) by the gate-to-ground capacitance. The voltage at the source of the external MOSFET follows the gate voltage, so the load dV/dt is the same as the gate dV/dt. Inrush current is the product of the dV/dt and the load capacitance. The time to start up tsU is the hot-swap voltage Vs divided by the output dV/dt.

Be sure to choose an external MOSFET that can handle the power dissipated during startup. The inrush current is roughly constant during startup and the voltage drop across the MOSFET (drain to source) decreases linearly as the load capacitance charges. The resulting power dissipation is, therefore, roughly equivalent to a single pulse of magnitude (V_S x inrush current)/2 and

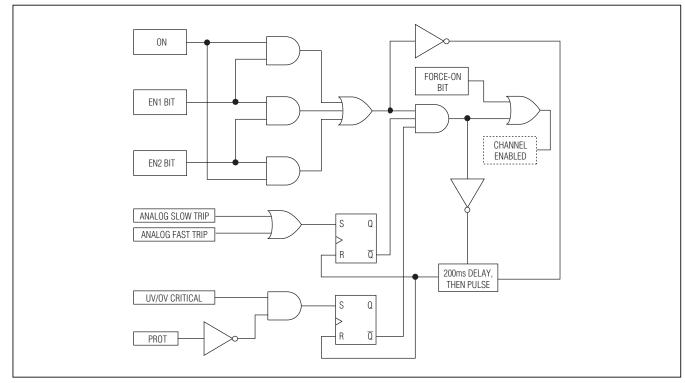


Figure 1. Channel On-Off Control Logic Functional Schematic

duration tsU. Refer to the thermal resistance charts in the MOSFET data sheet to determine the junction temperature rise during startup, and ensure that this does not exceed the maximum junction temperature for worstcase ambient conditions.

Circuit-Breaker Protection

As the channel is turned on and during normal operation, two analog comparators are used to detect an overcurrent condition by sensing the voltage across an external resistor connected between SENSE and MON. If the voltage across the sense resistor is less than the slow-trip and fast-trip circuit-breaker thresholds, the GATE output remains high. If either of the thresholds is exceeded due to an overcurrent condition, the gate of the MOSFET is pulled down to MON by an internal 500mA current source.

The higher of the two comparator thresholds, the fast trip, is set by an internal 8-bit DAC (see Table 7), within one of three configurable full-scale current-sense

ranges: 25mV, 50mV, or 100mV (see Tables 6a and 6b). The 8-bit fast-trip threshold DAC can be programmed from 40% to 100% of the selected full-scale currentsense range. The slow-trip threshold follows the fast-trip threshold as one of four programmable ratios, set by the ifast2slow register (see Tables 4a and 4b).

The fast-trip threshold is always higher than the slow-trip threshold, and the fast-trip comparator responds very quickly to protect the system against sudden, severe overcurrent events. The slower response of the slowtrip comparator varies depending upon the amount of overdrive beyond the slow-trip threshold. If the overdrive is small and short lived, the comparator will not shut down the affected channel. As the overcurrent event increases in magnitude, the response time of the slowtrip comparator decreases. This scheme provides good noise rejection and spurious overcurrent transients near the slow-trip threshold, while aggressively protecting the system against larger overcurrent events that occur as a result of a load fault.

Table 4a. ifast2slow Register Format

Description:		Current thre	Current threshold fast-to-slow setting bits							
Resister Title	:	ifast2slow	ifast2slow							
Register Add	lress:	0x30								
								RESET		
R	R	R	R	R/W	R/W	R/W	R/W	VALUE		
_	_		_	Unused	Unused	FS1	FS0	0x0F		
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0			

Table 4b. Setting Fast-Trip to Slow-Trip Threshold Ratio

FS1	FS0	FAST-TRIP TO SLOW-TRIP RATIO (%)
0	0	125
0	1	150
1	0	175
1	1	200

Setting Circuit-Breaker Thresholds

To select and set the device slow-trip and fast-trip comparator thresholds, use the following procedure:

- Select one of four ratios between the fast-trip threshold and the slow-trip threshold: 200%, 175%, 150%, or 125%. A system that experiences brief but large transient load currents should use a higher ratio, whereas a system that operates continuously at higher average load currents might benefit from a smaller ratio to ensure adequate protection. The ratio is set by writing to the ifast2slow register. (The default setting on power-up is 200%.)
- 2) Determine the slow-trip threshold VTH,ST based on the anticipated maximum continuous load current during normal operation, and the value of the current-sense resistor. The slow-trip threshold should include some margin (possibly 20%) above the maximum load current to prevent spurious circuit-breaker shutdown and to accommodate passive component tolerances:

VTH,ST = RSENSE × ILOAD,MAX × 120%

3) Calculate the necessary fast-trip threshold VTH,FT based on the ratio set in step 1:

VTH,FT = VTH,ST x (ifast2slow ratio)

4) Select one of the three maximum current-sense ranges: 25mV, 50mV, or 100mV. The current-sense

range is initially set upon power-up by the state of the IRNG input, but can be altered at any time by writing to the status2 register. For maximum accuracy and best measurement resolution, select the lowest current-sense range that is larger than the VTH,FT value calculated in step 3.

5) Program the fast-trip and slow-trip thresholds by writing an 8-bit value to the dac_fast register. This 8-bit value is determined from the desired V_{TH,ST} value that was calculated in step 2, the threshold ratio from step 1, and the current-sense range from step 4:

The device provides a great deal of system flexibility because the current-sense range, DAC setting, and threshold ratio can be changed "on the fly" for systems that must protect a wide range of interchangeable load devices, or for systems that control the allocation of power to smart loads. Table 5 shows the specified ranges for the fast-trip and slow-trip thresholds for all combinations of current-sense range and threshold ratio.

When an overcurrent event causes the device to shut down the power channel, the open-drain FAULT output alerts the system. Figure 2 shows the operation and faultmanagement flowchart.

Table 5. Specified Current-Sense and Circuit-Breaker Threshold Ranges

IRNG INPUT	DAC OUTPUT RANGE (DEFAULT = FULL SCALE) (mV)	FAST-TRIP THRESHOLD RANGE (mV)	GAIN (2 BIT) (VFAST/ VsLow) ifast2slow (DEFAULT = 11)	SLOW-TRIP THRESHOLD RANGE (mV)
			00 (125%)	8.00 to 20.00
Low	10 to 25	10 to 25	01 (150%)	6.67 to 16.67
Low	101025	10 10 25	10 (175%)	5.71 to 14.29
			11 (200%)	5.00 to 12.50
			00 (125%)	16.00 to 40.00
Llich	001 50	00 to 50	01 (150%)	13.33 to 33.33
High	20 to 50	20 to 50	10 (175%)	11.48 to 28.57
			11 (200%)	10.00 to 25.00
			00 (125%)	32.00 to 80.00
Linconnected	40 to 100	10 to 100	01 (150%)	26.67 to 66.67
Unconnected	40 to 100	40 to 100	10 (175%)	22.86 to 57.14
			11 (200%)	20.00 to 50.00

Table 6a. IRNG Input Status Register Format

Description:		Fast-trip th	Fast-trip threshold maximum range-setting bits, from IRNG three-state input								
Resister Title:		status2									
Register Add	ress:	0x33									
								RESET			
R	R	R	R	R/W	R/W	R/W	R/W	VALUE			
	_	_		Unused	Unused	IRNG1	IRNG0] —			
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0				

Table 6b. Setting Current-Sense Range

IRNG PIN STATE	IRNG PIN STATE IRNG1		MAXIMUM CURRENT-SENSE SIGNAL (mV)
Low	1	0	25
High	0	1	50
Open	0	0	100

Table 7. dac_ch_ Register Format

Description: Fast-com			ator threshold E	OAC setting				
Register Title:		dac_fast						
Register Addr	esses:	0x2E						
								RESET
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	VALUE
DAC[7]	DAC[6]	DAC[5]	DAC[4]	DAC[3]	DAC[2]	DAC[1]	DAC[0]	0xBF
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	

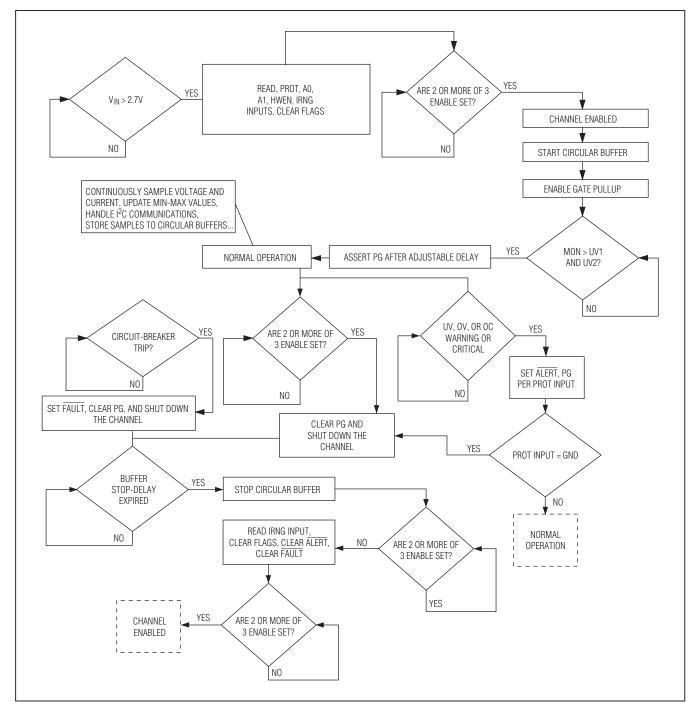


Figure 2. Operation and Fault-Management Flowchart for Hot-Swap Channel

Digital Current Monitoring

The current-sense signal is sampled by the internal 10-bit, 10ksps ADC, and the most recent results are stored in registers for retrieval through the I²C interface. The current conversion values are 10 bits wide, with the 8 high-order bits written to one 8-bit register and the 2 low-order bits written to the next-higher 8-bit register address (Tables 8 and 9). This allows use of just the high-order byte in applications where 10-bit precision is not required. This split 8-bit/2-bit storage scheme is used

throughout the device for ADC conversion results and digital comparator thresholds.

Once the PG output is asserted, the current-sense samples are continuously compared to the programmable overcurrent warning register value. If the measured current value exceeds the warning level, the ALERT output is asserted. The device response to this digital comparator is not altered by the setting of the PROT input (Tables 10 and 11).

Table 8. ADC Current-Conversion Results Register Format (High-Order Bits)

Description:		Most recent c	Most recent current-conversion result, high-order bits [9:2]							
Register Title:		adc_cs_msb	adc_cs_msb							
Register Addr	esses:	0x00								
								RESET		
R	R	R	R	R	R	R	R	VALUE		
inew_9	inew_8	inew_7	inew_6	inew_5	inew_4	inew_3	inew_2	0x00		
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	_		

Table 9. ADC Current-Conversion Results Register Format (Low-Order Bits)

Description:		Most recent c	Most recent current-conversion result, low-order bits [0:1]						
Register Title:		adc_cs_ lsb							
Register Add	resses:	0x01							
								RESET	
R	R	R	R	R	R	R	R	VALUE	
	_		—		_	inew_1	inew_0	0x00	
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0		

Table 10. Overcurrent Warning Threshold Register Format (High-Order Bits)

Description:		Overcurrent warning threshold high-order bits [9:2]						
Register Title	:	oithr_msb						
Register Add	resses:	0x22						
								RESET
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	VALUE
oi_9	oi_8	oi_7	oi_6	oi_5	oi_4	oi_3	oi_2	0xFF
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	

Table 11. Overcurrent Warning Threshold Register Format (Low-Order Bits)

Description:		Overcurrent w	Overcurrent warning threshold low-order bits [1:0]							
Register Title:		oithr_lsb								
Register Addr	esses:	0x23								
								RESET		
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	VALUE		
	—	—			—	oi_1	oi_0	0x03		
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0			

Minimum and Maximum Value Detection for Current-Measurement Values

Current-sense measurement values from the ADC are continuously compared with the contents of minimumand maximum-value registers, and if the most recent measurement exceeds the stored maximum, or is less than the stored minimum, the corresponding register is updated with the new value. These "peak-detection" registers are read/write accessible through the I²C interface (Tables 12–15). The minimum-value registers are reset to 0xFF and the maximum-value registers are reset to 0x00. These reset values are loaded upon startup of the channel or at any time as commanded by register peak_log_rst (Table 35).

Table 12. ADC Minimum Current-Conversion Register Format (High-Order Bits)

Description:		Minimum current-conversion result high-order bits [9:2]						
Register Title: min_cs_msb								
Register Addre	esses:	0x08						
								RESET
R	R	R	R	R	R	R	R	VALUE
imin_9	imin_8	imin_7	imin_6	imin_5	imin_4	imin_3	imin_2	0xFF
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	

Table 13. ADC Minimum Current-Conversion Register Format (Low-Order Bits)

Description:		Minimum curr	ent-conversior	n result low-ord	ler bits [1:0]			
Register Title:		min_cs_ lsb						
Register Addr	esses:	0x09						
								RESET
R	R	R	R	R	R	R	R	VALUE
_	_	—	—	_	_	imin_1	imin_0	0x03
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	

Table 14. ADC Maximum Current-Conversion Register Format (High-Order Bits)

Description:		Maximum cur	Maximum current-conversion result high-order bits [9:2]						
Register Title:		max_cs_msb	max_cs_msb						
Register Addr	esses:	0x0A)x0A						
								RESET	
R	R	R	R	R	R	R	R	VALUE	
imax_9	imax_8	imax_7	imax_6	imax_5	imax_4	imax_3	imax_2	0x00	
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0		

Table 15. ADC Maximum Current-Conversion Register Format (Low-Order Bits)

Description:		Maximum cur	Maximum current-conversion result low-order bits [1:0]							
Register Title:		max_cs_lsb	max_cs_lsb							
Register Add	resses:	0x0B								
								RESET		
R	R	R	R	R	R	R	R	VALUE		
	_		_	_	_	imax_1	imax_0	0x00		
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0			

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Digital Voltage Monitoring and Power-Good Output

The voltage at the load (MON input) is sampled by the internal ADC. The MON full-scale voltage can be set to 16V, 8V, 4V, or 2V by writing to register mon_range. The default range is 16V (Tables 16 and 17).

The most recent voltage-conversion results can be read from the adc_mon_msb and adc_mon_lsb registers (see Tables 18 and 19).

Digital Undervoltage- and Overvoltage-Detection Thresholds

The most recent voltage values are continuously compared to four programmable limits, comprising two undervoltage (UV) levels (see Tables 20 to 23) and two overvoltage (OV) levels (see Tables 24 to 27).

If PG is asserted and the voltage is outside the warning limits, the $\overline{\text{ALERT}}$ output is asserted low. Depending on the status of the prot[] bits in register status1[7:6], the

Table 16. ADC Voltage Monitor Settings Register Format

Description:		ADC voltage	monitor full-sc	ale range settir	ngs (for MON i	nput)		
Register Title:		mon_range	mon_range					
Register Add	resses:	0x18	x18					
								RESET
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	VALUE
	_	—	—	Unused	Unused	MON_rng1	MON_rng0	0x00
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	—

Table 17. ADC Full-Scale Voltage Setting

MON_rng1	MON_rng0	ADC FULL-SCALE VOLTAGE (V)
0	0	16
0	1	8
1	0	4
1	1	2

Table 18. ADC Voltage-Conversion Result Register Format (High-Order Bits)

Description:		Most recent v	oltage-conver	sion result, hig	h-order bits [§	9:2]			
Register Title:		adc_mon_ms	dc_mon_msb						
Register Addr	esses:	0x02	Ix02						
								RESET	
R	R	R	R	R	R	R	R	VALUE	
vnew_9	vnew_8	vnew_7	vnew_6	vnew_5	vnew_4	vnew_3	vnew_2	0x00	
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	- 	

Table 19. ADC Voltage-Conversion Result Register Format (Low-Order Bits)

Description:		Most recent v	Most recent voltage-conversion result, low-order bits [1:0]					
Register Title:		adc_mon_lsb	adc_mon_lsb					
Register Addr	esses:	0x03	×03					
								RESET
R	R	R	R	R	R	R	R	VALUE
	_			_	_	vnew_1	vnew_0	0x00
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	

device can also deassert the PG output or turn off the external MOSFET when the voltage is outside the critical limits (see Figure 3). Table 28 shows the behavior for the three possible states of the PROT input. Note that the PROT input does not affect the device response to the UV or OV warning digital comparators; it only determines the system response to the critical digital comparators (see Tables 3a, 3b, and 28).

In a typical application, the UV1 and OV1 thresholds would be set closer to the nominal output voltage, and the UV2 and OV2 thresholds would be set further from nominal. This provides a "progressive" response to a voltage excursion. However, the thresholds can be configured in any arrangement or combination as desired to suit a given application.

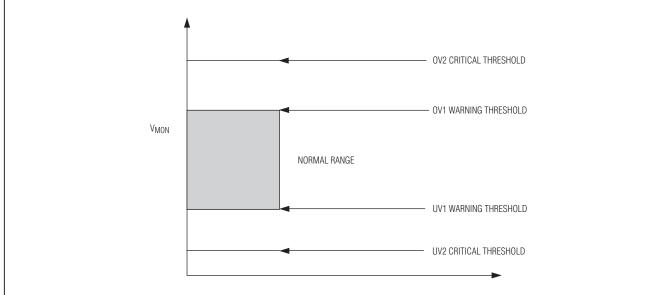


Figure 3. Graphical Representation of Typical UV and OV Thresholds Configuration

Table 20. Undervoltage Warning Threshold Register Format (High-Order Bits)

Description:		Undervoltage	warning three	shold high-ord	er bits [9:2]			
Register Title:		uv1th_msb	uv1th_msb					
Register Addr	esses:	0x1A	Jx1A					
								RESET
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	VALUE
uv1_9	uv1_8	uv1_7	uv1_6	uv1_5	uv1_4	uv1_3	uv1_2	0x00
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	—

Table 21. Undervoltage Warning Threshold Register Format (Low-Order Bits)

Description:		Undervoltage	Undervoltage warning threshold low-order bits [1:0]						
Register Titles	S:	uv1th_lsb	uv1th_lsb						
Register Add	resses:	0x1B							
								RESET	
R	R	R	R	R	R	R/W	R/W	VALUE	
	_	_	—		_	uv1_1	uv1_0	0x00	
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	—	

Table 22. Undervoltage Critical Threshold Register Format (High-Order Bits)

Description:		Undervoltage	e critical thresh	nold high-orde	r bits [9:2]			
Register Title:		uv2th_msb	uv2th_msb					
Register Add	gister Addresses: 0x1C							
								RESET
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	VALUE
uv2_9	uv2_8	uv2_7	uv2_6	uv2_5	uv2_4	uv2_3	uv2_2	0x00
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	

Table 23. Undervoltage Critical Threshold Register Format (Low-Order Bits)

Description:		Undervoltage	e critical thresh	old low-order	bits [1:0]			
Register Title:		uv2th_lsb						
Register Add	esses:	0x1D						
								RESET
R	R	R	R	R	R	R/W	R/W	VALUE
	—		—	—		uv2_1	uv2_0	0x00
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	—

Table 24. Overvoltage Warning Threshold Register Format (High-Order Bits)

Description:		Overvoltage	Overvoltage warning threshold high-order bits [9:2]						
Register Title:		ov1thr_msb	ov1thr_msb						
Register Addr	esses:	0x1E	x1E						
								RESET	
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	VALUE	
ov1_9	ov1_8	ov1_7	ov1_6	ov1_5	ov1_4	ov1_3	ov1_2	0xFF	
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0		

Table 25. Overvoltage Warning Threshold Register Format (Low-Order Bits)

Description:		Overvoltage warning threshold low-order bits [1:0]								
Register Title:	Title: ov1thr_lsb									
Register Addr	esses:	0x1F	0x1F							
						RESET				
R	R	R	R	R	R	R/W	R/W	VALUE		
			_		_	ov1_1	ov1_0	0x03		
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	—		

Table 26. Overvoltage Critical Threshold Register Format (High-Order Bits)

Description:		Overvoltage	Overvoltage critical threshold high-order bits [9:2]							
Register Title:		ov2thr_msb								
Register Add	resses:	0x20								
								RESET		
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	VALUE		
ov2_9	ov2_8	ov2_7	ov2_6	ov2_5	ov2_4	ov2_3	ov2_2	0xFF		
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	_		

Table 27. Overvoltage Critical Threshold Register Format (Low-Order Bits)

Description:		Overvoltage	critical thresho	old low-order k	oits [1:0]			
Register Title	Э:	ov2thr_lsb						
Register Add	dresses:	0x21						
								RESET
R	R	R	R	R	R/W	R/W	R/W	VALUE
		_	—			ov2_1	ov2_0	0x03
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	

Table 28. PROT Input and prot[] Bits

PROT INPUT STATE	prot[1]	prot[0]	UV/OV WARNING ACTION	UV/OV CRITICAL ACTION
Low	0	0	Assert ALERT	Assert ALERT, clear PG, shut down channel
High	0	1	Assert ALERT	Assert ALERT, clear PG
Unconnected	1	0	Assert ALERT	Assert ALERT

Table 29. status3 Register Format

Description:		Power-good status register: POL, ALERT, and power-good bits								
Register Title	:	status3	status3							
Register Add	ress:	0x34								
								RESET		
R	R	R	R/W	R	R	R	R	VALUE		
_	_	POL	ALERT	—	—	Unused	pg[0]	—		
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0			

Table 30a. Power-Good Assertion Delay-Time Register Format

Description:		Power-good	Power-good assertion delay-time register									
Register Title	:	pgdly	gdly									
Register Add	ress:	0x38										
								RESET				
R	R	R	R	R/W	R/W	R/W	R/W	VALUE				
—	_	—	—	Unused	Unused	pgdly1	pgdly0	0x00				
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	—				

Table 30b. Power-Good Assertion Delay

pgdly1	pgdly0	PG ASSERTION DELAY (ms)
0	0	50
0	1	100
1	0	200
1	1	400

Power-Good Detection and PG Output

The PG output is asserted when the voltage at MON is between the undervoltage and overvoltage critical limits. The status of the power-good signal is maintained in register status3[0]. A value of 1 in the pg[] bit indicates a power-good condition, regardless of the POL setting, which only affects the PG output pin polarity. The opendrain PG output can be configured for active-high or active-low status indication by the state of the POL input (see Table 29).

The POL input sets the value of status3[5], which is a read-only bit; the state of the POL input can be changed at any time during operation and the polarity of the PG output changes accordingly.

The assertion of the PG output is delayed by a userselectable time delay of 50ms, 100ms, 200ms, or 400ms (see Tables 30a and 30b).



Minimum and Maximum Value Detection for Voltage-Measurement Values

All voltage-measurement values are compared with the contents of minimum- and maximum-value registers, and if the most recent measurement exceeds the stored maximum or is less than the stored minimum, the corresponding register is updated with the new value. These

peak-detection registers are read accessible through the I²C interface (see Tables 31 to 34). The minimum-value registers are reset to 0xFF, and the maximum-value registers are reset to 0x00. These reset values are loaded upon startup or at any time as commanded by register peak_log_rst (see Table 35).

Table 31. ADC Minimum Voltage Conversion Register Format (High-Order Bits)

Description:		Minimum volt	Minimum voltage conversion result, high-order bits [9:2]								
Register Title:		min_mon_ms	min_mon_msb								
Register Addr	esses:	0x0C	KOC								
R	R	R	R	R	R	R	R	VALUE			
vmin_9	vmin_8	vmin_7	vmin_6	vmin_5	vmin_4	vmin_3	vmin_2	0xFF			
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	—			

Table 32. ADC Minimum Voltage-Conversion Register Format (Low-Order Bits)

Description:		Minimum voltage-conversion result, low-order bits [1:0]								
Register Title	:	min_mon_lsb								
Register Add	resses:	0x0D)x0D							
R	R	R	R	R	R	R	R	VALUE		
	_		_	—	_	vmin_1	vmin_0	0x03		
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	—		

Table 33. ADC Maximum Voltage-Conversion Register Format (High-Order Bits)

Description: Register Title:									
Register Addr	resses:	0x0E							
								RESET	
R	R	R	R	R	R	R	R	VALUE	
vmax_9	vmax_8	vmax_7	vmax_6	vmax_5	vmax_4	vmax_3	vmax_2	0x00	
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	—	

Table 34. ADC Maximum Voltage-Conversion Register Format (Low-Order Bits)

			•		-	•			
Description:		Maximum vol	tage-conversion	on result, low-o)]				
Register Title	:	max_mon_lsb)						
Register Add	resses:	0x0F)x0F						
								RESET	
R	R	R	R	R	R	R	R	VALUE	
		_			_	vmax_1	vmax_0	0x00	
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	—	

Using the Voltage and Current Peak-Detection Registers

The voltage and current minimum- and maximum-value records in register locations 0x08 through 0x17 can be reset by writing a 1 to the appropriate location in register peak_log_rst (see Table 35). The minimum-value registers are reset to 0xFF, and the maximum-value registers are reset to 0x000.

As long as a bit in peak_log_rst is 1, the corresponding peak-detection registers are disabled and are "cleared" to their power-up reset values. The voltage and current

minimum- and maximum-detection register contents can be "held" by setting bits in register peak_log_hold (see Table 36). Writing a 1 to a location in peak_log_hold locks the register contents for the corresponding signal and stops the min/max detection and logging; writing a 0 enables the detection and logging. Note that the peakdetection registers cannot be cleared while they are held by register peak_log_hold.

The combination of these two control registers allows the user to monitor voltage and current peak-to-peak values during a particular time period.

Table 35. Peak-Detection Reset-Control Register Format

Description:		Reset control bits for peak-detection registers							
Register Title	:	peak_log_rst							
Register Add	ress:	0x41							
								RESET	
R	R	R	R	R/W	R/W	R/W	R/W	VALUE	
—	_	_		Unused	Unused	v_rst	i_rst	0x00	
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0		

Table 36. Peak-Detection Hold-Control Register Format

Description:				letection registe	ers			
Register Title):	peak_log_ho	ld					
Register Add	tress:	0x42						
								RESET
R	R	R	R	R/W	R/W	R/W	R/W	VALUE
		_	_	Unused	Unused	Ch0_v_hld	Ch0_i_hld	0x00
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	

Table 37. OI Warning Comparators Deglitch Enable Register Format

Description:		Deglitch enable register for overcurrent warning digital comparators								
Register Title	:	dgl_i								
Register Add	ress:	0x3C								
								RESET		
R	R	R	R	R	R	R/W	R/W	VALUE		
_	—	—	—	—	_	Unused	dgl_i	0x00		
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	_		

Table 38. UV Warning and Critical Comparators Deglitch Enable Register Format

Description:		Deglitch enal	ole register for	undervoltage	warning and	critical digital	comparators	
Register Title	:	dgl_uv						
Register Add	ress:	0x3D						
								RESET
R	R	R	R	R/W	R/W	R/W	R/W	VALUE
		—	—	Unused	Unused	dgl_uv2	dgl_uv1	0x00
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	_

Table 39. OV Warning and Critical Comparators Deglitch Enable Register Format

Description:		Deglitch ena	ble register for	r overvoltage w	arning and c	ritical digital c	omparators	
Register Title	:	dgl_ov						
Register Add	ress:	0x3E						
								RESET
R	R	R	R	R/W	R/W	R/W	R/W	VALUE
_	_	—	_	Unused	Unused	dgl_ov2	dgl_ov1	0x00
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	

Deglitching of Digital Comparators

The five digital comparators (undervoltage/overvoltage warning and critical, overcurrent warning) all have a user-selectable deglitching feature that requires two consecutive positive compares before the device takes action as determined by the particular compare and the setting of the PROT input.

The deglitching functions are enabled or disabled by registers dgl_i, dgl_uv, and dgl_ov (Tables 37, 38, and 39). Writing a 1 to the appropriate bit location in these registers enables the deglitch function for the corresponding digital comparator.

Circular Buffer The device features two 10-bit "circular buffers" (in volatile memory) that contain a history of the 50 most-recent voltage and current digital-conversion results. These circular buffers can be read back through the I²C interface. The recording of new data to the buffer for a given signal is stopped under any of the following conditions:

- The hot-swap channel is shut down because of a fault condition.
- A read of the circular buffer base address is performed through the I²C interface.
- The hot-swap channel is turned off by a combination of the EN1, EN2, or ON signals.

The buffers allow the user to recall the voltage and current waveforms for analysis and troubleshooting. The buffer contents are accessed through the I²C interface at two fixed addresses in the device register address space (see Table 40).

Each buffer can also be stopped under user control by register cbuf_chx_store (see Table 41).

The contents of a buffer can be retrieved as a block read of either fifty 10-bit values (spanning 2 bytes each) or of 50 high-order bytes, depending on the per-signal bit settings of register cbufrd_hibyonly (see Table 42).

If the circular buffer contents are retrieved as 10-bit data, the first byte read-out is the high-order 8 bits of the 10-bit sample, and the second byte read-out contains the 2 least-significant bits (LSBs) of the sample. This is repeated for each of the 50 samples in the buffer. Thus, 2 bytes must be read for each 10-bit sample retrieved. Conversely, if the buffer contents are retrieved as 8-bit data, then each byte read-out contains the 8 MSBs of each successive sample. It is important to remember that in 10-bit mode, 100 bytes must be read to extract the entire buffer contents, but in 8-bit mode, only 50 bytes must be read.

The circular buffer system has a user-programmable "stop delay" that specifies a certain number of sample cycles to continue recording to the buffer after a shutdown occurs. This delay value is stored in register cbuf_dly_stop[5:0] (see Table 43). The default (reset) value of the buffer stop delay is 25 samples, which means that an equal number of samples are stored in the buffer preceding and following the moment of the shutdown event. The buffer stop delay is analogous to an oscilloscope trigger delay because it allows the device to record what happened both immediately before and after a shutdown. In other words, when the contents of a circular buffer are read out of the device, the shutdown event is by default located in the middle of the recorded data. The balance of data before and after an event can be altered by writing a different value (between 0 and 50) to the buffer stop-delay register.

Latched-Off Fault Management

In the event of an overcurrent, undervoltage, or overvoltage condition that results in the shutdown of the hotswap channel, the device remains latched off.

To restart the latched-off channel, the user must either cycle power to the IN input, or toggle the ON pin, EN1 bit, or the EN2 bit.

Table 40. Circular Buffer Read Addresses

ADDRESS	NAME	DESCRIPTION
0x46	cbuf_ba_v	Base address for voltage buffer block read
0x47	cbuf_ba_i	Base address for current buffer block read

Table 41. Circular Buffer Control Register Format

Description:		Circular buff	er run-stop co	ntrol register (per-buffer cor	ntrol: 1 = run, 0 =	= stop)	
Register Title	:	cbuf_chx_ste	sbuf_chx_store					
Register Add	ress:	0x19	x19					
								RESET
R	R	R	R	R/W	R/W	R/W	R/W	VALUE
	_	_	—	Unused	Unused	Ch0_i_run	Ch0_v_run	0x0F
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	—

Table 42. Circular Buffer Resolution Register Format

Description:				olution: high-ord -order byte out	, , , , , , , , , , , , , , , , , , ,				
Register Title: cbufrd_hibyonly									
Register Address: 0x3F									
								RESET	
R	R	R	R	R/W	R/W	R/W	R/W	VALUE	
	_	— — Unused Unused i_res v_res 0							
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0		

Table 43. Circular Buffer Stop-Delay Register Format

Description	1:			, 0	per between 0 a Iffer stops storir		that are to be re	ecorded to a		
Register Tit	tle:	cbuf_dly_stop	buf_dly_stop							
Register Ad	ddress:	0x40								
								RESET		
R	R	R/W	R/W	R/W	R/W	R/W	R/W	VALUE		
0	0	Stop_dly[5]	Stop_dly[4]	Stop_dly[3]	Stop_dly[2]	Stop_dly[1]	Stop_dly[0]	0x19		
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0			

Table 44. Force-On Control Register Format

Description:		Force-on con	trol register					
Register Title	Register Title: foset							
Register Add	Register Address: 0x3A							
								RESET
R	R	R	R	R	R	R/W	R/W	VALUE
0	0	0	0	0	0	Unused	fo	0x00
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	

Table 45. Force-On Key Register Format

Description:		Force-on key	register (must	contain 0xA5 to	unlock force-c	on feature)		
Register Title	e:	fokey						
Register Ad	dress:	0x39						
								RESET
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	VALUE
fokey[7]	fokey[6]	fokey[5]	fokey[4]	fokey[3]	fokey[2]	fokey[1]	fokey[0]	0x00
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	—

Force-On Function

When the force-on bit is set to 1 in register foset[0] (see Table 44), the channel is enabled regardless of the ON pin voltage or the EN1 and EN2 bits in register chxen. In forced-on operation, all functions operate normally with the notable exception that the channel does not shut down due to any fault conditions that may arise.

There is a force-on key register fokey that must be set to 0xA5 in order for the force-on function to become active (see Table 45). If this register contains any value other

than 0xA5, writing 1 to the force-on bits in register foset has no effect. This provides protection against accidental force-on operation that might otherwise be caused by an erroneous I^2C write.

Fault Logging and Indications

The device provides detailed information about any fault conditions that have occurred. The FAULT output specifically indicates a circuit-breaker shutdown event, while the ALERT output is asserted whenever a problem has occurred that requires attention or interaction.

Fault Dependency

If a fault event occurs (digital UV warning/critical, digital OV warning/critical, or digital overcurrent warning), the fault is logged by setting a corresponding bit in registers fault0, fault1, or fault2 (see Tables 46, 47, and 48).

Likewise, circuit-breaker shutdown events are logged in register status0[7:0] (see Table 49).

IFAULTS indicates the overcurrent status from slow comparator. IFAULTF indicates overcurrent status from fast comparator. The status of FAULT reflects the OR operation of IFAULTS and IFAULTF.

These fault register bits latch upon a fault condition, and must be reset manually by restarting as described in the *Latched-Off Fault Management* section.

Table 46. Undervoltage Status Register Format

Description:		Undervoltage detection sta	0 1	are status regis	ster (warning [(0] and critical [4] undervoltag	ge event-
Register Title	:	fault0						
Register Add	lress:	0x35						
								RESET
R	R	R/C	R/C	R	R	R/C	R/C	VALUE
_		Unused	uv1	—		Unused	uv1	0x00
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	

Table 47. Overvoltage Status Register Format

Description:		Overvoltage c status)	ligital-compare	status register	(warning [0] an	d critical [4] ove	ervoltage even	t-detection
Register Titl	e:	fault1						
Register Ad	dress:	0x36						
								RESET
R	R	R/C	R/C	R	R	R/C	R/C	VALUE
	_	Unused	ov2			Unused	ov1	0x00
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	

Table 48. Overcurrent Warning Status Register Format

Description	1:	Overcurrent d	igital-compare	status register (overcurrent wa	rning event-dete	ection status)	
Register Title: fau		fault2						
Register Ac	ddress:	0x37						
								RESET
R	R	R	R	R	R	R/C	R/C	VALUE
—	_	—	—	_	—	Unused	oi	0x00
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	

Table 49. Circuit-Breaker Event Logging Register Format

Description: Circuit-breaker slow- and fast-trip event logging								
Register Title):	status0						
Register Add	tress:	0x31						
								RESET
R	R	R	R	R	R	R	R	VALUE
—	_	Unused	IFAULTS	_	_	Unused	IFAULTF	0x00
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	

FAULT Output

LED Set Registers

When an overcurrent event (fast trip or slow trip) causes the device to shut down the hot-swap channel, an opendrain FAULT output is asserted low. Note that the FAULT output is not asserted for shutdowns caused by critical undervoltage or overvoltage events.

The $\overline{\text{FAULT}}$ output is cleared when the channel is disabled by pulling ON low or by clearing the bits in register chxen.

ALERT Output

ALERT is an open-drain output that is asserted low any time that a fault or other condition requiring attention has occurred. The state of the ALERT output is also indicated by status3[4].

The $\overline{\text{ALERT}}$ output is the logical NOR of registers 0x31, 0x35, 0x36, and 0x37, so when the $\overline{\text{ALERT}}$ output goes low, the system microcontroller should query these registers through the I²C interface to determine the cause of the $\overline{\text{ALERT}}$ assertion.

The device has four open-drain LED drivers/user-programmable GPIOs. When programmed as LED drivers, each driver can sink up to 25mA of current. Table 50 shows the register that enables the drivers as either LED drivers or GPIOs.

When any of the LED_ Set bit in the register is set to 1, the corresponding open-drain LED driver is turned off. The LED_Flash bits enable each corresponding LED driver to flash on and off at 1Hz frequency regardless of the condition of the corresponding LED_ Set bit.

Bits 7–4 in Table 51 set the LED flashing drivers to be either in-phase or out-of-phase with the internal 1Hz clock. Bits 3–0 enable the 4μ A pullup current to the corresponding output.

Table 52 shows the LED state register. The LED state register is a read-only register. When the LEDs are disabled, the pins are configured as GPIOs. Applying an external voltage below 0.4V sets the GPIOs low and, applying an external voltage above 1.4V, sets the GPIOs high.

Table 50. LED_Flash/GPIO Enable Register Description: LED_flash/GPIO enable register Register Title: LED_flash

Register Address: 0x43								
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	RESET VALUE
LED4 Flash	LED3 Flash	LED2 Flash	LED1 Flash	LED4 Set	LED3 Set	LED2 Set	LED1 Set	0x0F
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	

Table 51. LED Phase/Weak Pullup Enable Register

Description:		LED phase/	weak pullup e	nable				
Register Title:		LED_ph_pu						
Register Add	dress:	0x44						
								RESET
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	VALUE
LED4	LED3	LED2	LED1	LED4 Weak	LED3 Weak	LED2 Weak	LED1 Weak	0,00
Phase	Phase	Phase	Phase	PU	PU	PU	PU	0x00

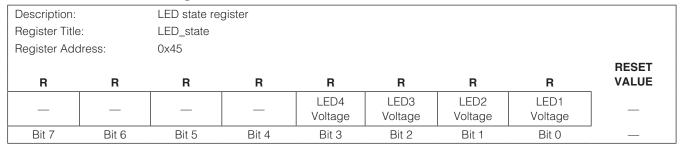


Table 52. LED State Register

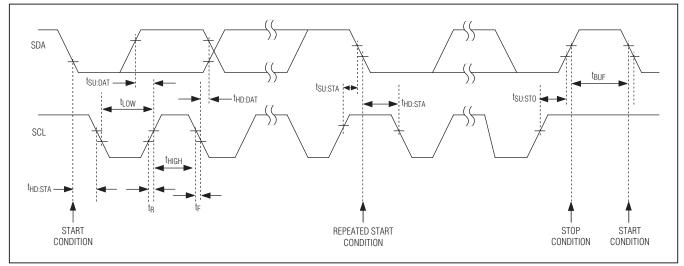


Figure 4. Serial-Interface Timing Details

I²C Serial Interface

The device features an I²C-compatible serial interface consisting of a serial data line (SDA) and a serial clock line (SCL). SDA and SCL allow bidirectional communication between the device and the master device at clock rates from 100kHz to 400kHz. The I²C bus can have several devices (e.g., more than one device, or other I²C devices in addition to the device) attached simultaneously. The A0 and A1 inputs set one of nine possible I²C addresses (see Table 53).

The 2-wire communication is fully compatible with existing 2-wire serial interface systems; Figure 4 shows the interface timing diagram. The device is a transmit/ receive slave-only device, relying upon a master device to generate a clock signal. The master device (typically a microcontroller) initiates data transfer on the bus and generates SCL to permit that transfer.

A master device communicates to the device by transmitting the proper address followed by command and/ or data words. Each transmit sequence is framed by a START (S) or Repeated START (SR) condition and a STOP (P) condition. Each word transmitted over the bus is 8 bits long and is always followed by an acknowledge pulse.

SCL is a logic input, while SDA is a logic input/opendrain output. SCL and SDA both require external pullup resistors to generate the logic-high voltage. Use $4.7 k\Omega$ for most applications.

ADDRESS INPUT I²C ADDRESS BITS STATE **A1 A0** ADDR 7 ADDR 6 ADDR 5 ADDR 4 ADDR 3 ADDR 2 ADDR 1 ADDR 0 0 R/W Low Low 0 1 1 1 0 1 Low High 0 1 1 1 0 0 1 R/W 0 R/W Open 0 1 0 0 Low 1 1 1 0 High Low 0 1 0 1 1 R/W High High 0 1 1 0 1 0 1 R/W High 0 0 0 0 R/W Open 1 1 1 Open Low 0 1 1 0 0 1 0 R/W High 0 0 0 R/W Open 0 1 1 1 Open Open 0 1 1 0 0 0 0 R/W

Table 53. Device Slave Address Settings

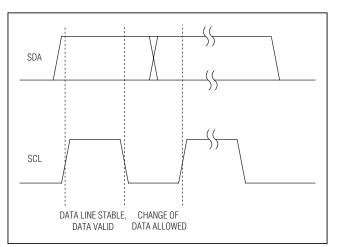


Figure 5. Bit Transfer

Bit Transfer

Each clock pulse transfers 1 data bit. The data on SDA must remain stable while SCL is high (see Figure 5); otherwise, the device registers a START or STOP condition (see Figure 6) from the master. SDA and SCL idle high when the bus is not busy.

START and STOP Conditions

Both SCL and SDA idle high when the bus is not busy. A master device signals the beginning of a transmission with a START condition (see Figure 3) by transitioning SDA from high to low while SCL is high. The master device issues a STOP condition (see Figure 6) by transitioning SDA from low to high while SCL is high. A STOP condition frees the bus for another transmission. The bus remains active if a Repeated START condition is generated, such as in the block read protocol (see Figure 7).

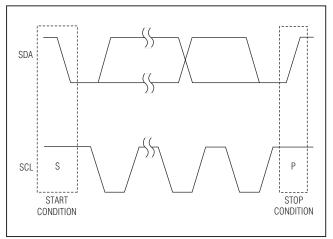


Figure 6. START and STOP Conditions

Early STOP Conditions

The device recognizes a STOP condition at any point during transmission except if a STOP condition occurs in the same high pulse as a START condition. This condition is not a legal I²C format. At least one clock pulse must separate any START and STOP condition.

Repeated START Conditions

A Repeated START (SR) condition may indicate a change of data direction on the bus. Such a change occurs when a command word is required to initiate a read operation (see Figure 4). SR may also be used when the bus master is writing to several I²C devices and does not want to relinquish control of the bus. The device serial interface supports continuous write operations with or without an SR condition separating them. Continuous read operations require SR conditions because of the change in direction of data flow.



SEND BYTE FORMAT WRITE WORD FORMAT Ρ WR S ADDRESS WR ACK DATA ACK S ADDRESS ACK COMMAND ACK DATA ACK DATA ACK Ρ 7 BITS 0 8 BITS 7 BITS 0 8 BITS 8 BITS 8 BITS SLAVE ADDRESS-COMMAND BYTE-DATA BYTE-PRESETS THE DATA BYTE-FIRST BYTE IS THE LSB OF SLAVE ADDRESS-EQUIVALENT TO CHIP-EQUIVALENT TO CHIP-INTERNAL ADDRESS POINTER. MSB OF THE THE EEPROM ADDRESS. SECOND SELECT LINE OF A SELECT LINE OF A FEPROM BYTE IS THE ACTUAL DATA. 3-WIRE INTERFACE. 3-WIRE INTERFACE. REGISTER BEING WRITTEN. **RECEIVE BYTE FORMAT** WRITE BYTE FORMAT S ADDRESS WR ACK DATA ACK Ρ S ADDRESS WR ACK COMMAND ACK DATA ACK Ρ 7 BITS 8 BITS 7 BITS 0 8 BITS 8 BITS 1 COMMAND BYTE-DATA BYTE-READS DATA FROM DATA BYTE-DATA GOES INTO THE SLAVE ADDRESS-SLAVE ADDRESS-EQUIVALENT TO CHIP-THE REGISTER COMMANDED BY EQUIVALENT TO CHIP-SELECTS REGISTER REGISTER SET BY THE COMMAND SELECT LINE OF A THE LAST READ BYTE OR WRITE SELECT LINE OF A BEING WRITTEN. BYTE IF THE COMMAND IS BELOW 3-WIRE INTERFACE. BYTE TRANSMISSION. ALSO 3-WIRE INTERFACE. 50h. IF THE COMMAND IS 80h, DEPENDENT ON A SEND BYTE. 81h. or 82h. THE DATA BYTE PRESETS THE LSB OF AN EEPROM ADDRESS **BLOCK WRITE FORMAT** BYTE DATA BYTE DATA BYTE DATA BYTE S ADDRESS WR ACK COMMAND ACK ACK ACK ACK ACK Ρ COUNT = N 1 Ν 7 BITS 0 8 BITS 8 BITS 8 BITS 8 BITS 8 BITS COMMAND BYTE-SLAVE ADDRESS-DATA BYTE-DATA GOES INTO THE REGISTER SET BY THE EQUIVALENT TO CHIP-PREPARES DEVICE COMMAND BYTE. FOR BLOCK SELECT LINE OF A OPERATION **3-WIRE INTERFACE BLOCK READ FORMAT** BYTE DATA BYTE DATA BYTE DATA BYTE ADDRESS WR ACK COMMAND ACK SR ADDRESS WR ACK ACK ACK ACK ACK Р S COUNT = 16Ν 7 BITS 0 8 BITS 7 BITS 10h 8 BITS 8 BITS 8 BITS 1 DATA BYTE-DATA GOES INTO THE REGISTER SET BY THE SLAVE ADDRESS-COMMAND BYTE-SLAVE ADDRESS-EQUIVALENT TO CHIP-EQUIVALENT TO CHIP-PREPARES DEVICE COMMAND BYTE. SELECT LINE OF A FOR BLOCK SELECT LINE OF A 3-WIRE INTERFACE. 3-WIRE INTERFACE. OPERATION. S = START CONDITION SHADED = SLAVE TRANSMISSION P = STOP CONDITION Sr = REPEATED START CONDITION

Figure 7. SMBus/I²C Protocols

Acknowledge

The acknowledge bit (ACK) is the 9th bit attached to any 8-bit data word. The receiving device always generates an ACK. The device generates an ACK when receiving an address or data by pulling SDA low during the 9th clock period (see Figure 8). When transmitting data, such as when the master device reads data back from the device, the device waits for the master device to generate an ACK. Monitoring ACK allows for detection of unsuccessful data transfers. An unsuccessful data transfer occurs if the receiving device is busy or if a system fault has occurred. In the event of an unsuccessful data transfer, the bus master should reattempt communication at a later time. The device generates a NACK after the slave address during a software reboot or when receiving an illegal memory address.

Send Byte

The send byte protocol allows the master device to send 1 byte of data to the slave device (see Figure 7). The send byte presets a register pointer address for a subsequent read or write. The slave sends a NACK instead of an ACK if the master tries to send an address that is not allowed. If the master sends a STOP condition, the internal address pointer does not change. The send byte procedure follows:

- 1) The master sends a START condition.
- The master sends the 7-bit slave address and a write bit (low).

- 3) The addressed slave asserts an ACK on SDA.
- 4) The master sends an 8-bit data byte.
- 5) The addressed slave asserts an ACK on SDA.
- 6) The master sends a STOP condition.

Write Byte

The write byte/word protocol allows the master device to write a single byte in the register bank or to write to a series of sequential register addresses. The write byte procedure follows:

- 1) The master sends a START condition.
- 2) The master sends the 7-bit slave address and a write bit (low).
- 3) The addressed slave asserts an ACK on SDA.
- 4) The master sends an 8-bit command code.
- 5) The addressed slave asserts an ACK on SDA.
- 6) The master sends an 8-bit data byte.
- 7) The addressed slave asserts an ACK on SDA.
- 8) The addressed slave increments its internal address pointer.
- 9) The master sends a STOP condition or repeats steps 6, 7, and 8.

To write a single byte to the register bank, only the 8-bit command code and a single 8-bit data byte are sent. The data byte is written to the register bank if the command code is valid.

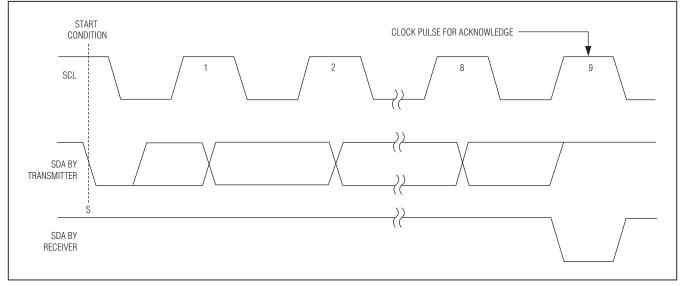


Figure 8. Acknowledge

Table 54. Circular Buffer Readout Sequence

READ-OUT ORDER	1ST OUT	2ND OUT	 48TH OUT	49TH OUT	50TH OUT
Chronological Number	1	2	 48	49	0

The slave generates a NACK at step 5 if the command code is invalid. The command code must be in the 0x00 to 0x45 range. The internal address pointer returns to 0x00 after incrementing from the highest register address.

Receive Byte

The receive-byte protocol allows the master device to read the register content of the device (see Figure 7). The EEPROM or register address must be preset with a send-byte protocol first. Once the read is complete, the internal pointer increases by one. Repeating the receive byte protocol reads the contents of the next address. The receive-byte procedure follows:

- 1) The master sends a START condition.
- 2) The master sends the 7-bit slave address and a read bit (high).
- 3) The addressed slave asserts an ACK on SDA.
- 4) The slave sends 8 data bits.
- 5) The slave increments its internal address pointer.
- 6) The master asserts an ACK on SDA and repeats steps 4, 5 or asserts a NACK and generates a STOP condition.

The internal address pointer returns to 0x00 after incrementing from the highest register address.

Address Pointers

Use the send-byte protocol to set the register address pointers before read and write operations. For the configuration registers, valid address pointers range from 0x00 to 0x45, and the circular buffer addresses are 0x46 to 0x49. Register addresses outside this range result in a NACK being issued from the device.

Circular Buffer Read

The circular buffer read operation is similar to the receive-byte operation. The read operation is triggered after any one of the circular buffer base addresses is loaded. During a circular buffer read, although all is transparent from the external world, internally the autoin-crement function in the I²C controller is disabled. Thus, it is possible to read one of the circular buffer blocks with a burst read without changing the virtual internal address corresponding to the base address. Once the master issues a NACK, the circular reading stops, and the default functions of the I²C slave bus controller are restored.

In 8-bit read mode, every I²C read operation shifts out a single sample from the circular buffer. In 10-bit mode, two subsequent I²C read operations shift out a single 10-bit sample from the circular buffer, with the high-order byte read first, followed by a byte containing the rightshifted 2 least-significant bits. Once the master issues a NACK, the read circular buffer operation terminates and normal I²C operation returns.

The data in the circular buffers is read back with the next-to-oldest sample first, followed by progressively more recent samples until the most recent sample is retrieved, followed finally by the oldest sample (see Table 54).

Chip Information

PROCESS: BICMOS

Package Information

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PACKAGE	PACKAGE	OUTLINE	LAND
TYPE	CODE	NO.	PATTERN NO.
32 TQFN-EP	T3255+4	<u>21-0140</u>	<u>90-0012</u>

Revision History

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	7/10	Initial release	—

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